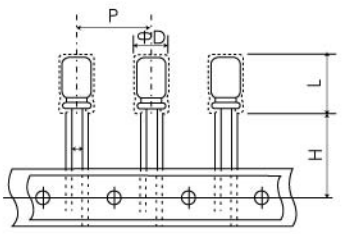
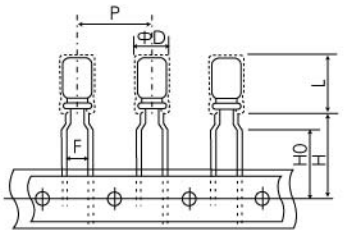
Radial Lead Taping

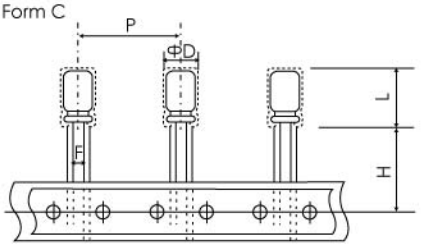
Lead Taping Capacitors for Automatic Insertion

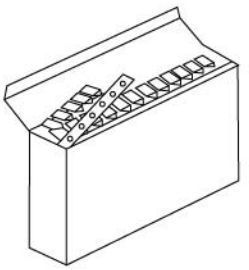
▪ Standard

Code	Case range		Dimensions				Form	External form Drawing	Packing Form
	ΦD	L (max)	H±0.75	Ho±0.5	F±0.5	P±0.1			
FF	4~5	5~13	17.5	16	2.5	12.7	B	Form A	Flat Box
	6.3	5~13	18.5	-	2.5	12.7	A		
	8	5~13	18.5	-	3.5	12.7	A		
	4~8	5~7	17.5	16	5.0	12.7	B	Form B	
	5~6.3	11~13	18.5						
	8	11~22	20.0						
	10	11~22	18.5	-			A	Form C	
	12.5	16~27	18.5	-		15.0			
	16~18	20~27	18.5	-	7.5	30.0	C		



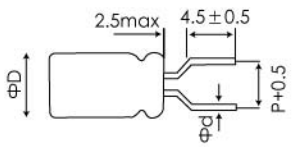




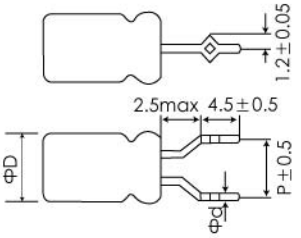


Lead Cut And Forming

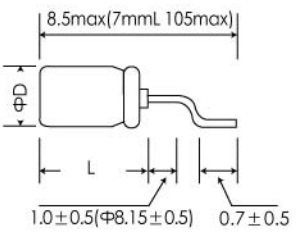
FC(Φ4,5,6.3,8)



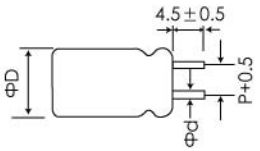
FM(Φ4,5,6.3,8)



FS(Φ3,4,5,6.3,8)

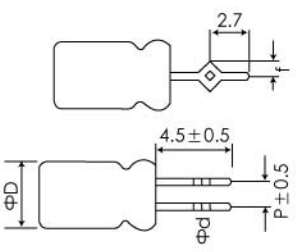


CC(Φ10, 12.5,16,18)

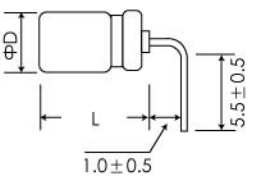


MC(Φ10,12.5,16,18)

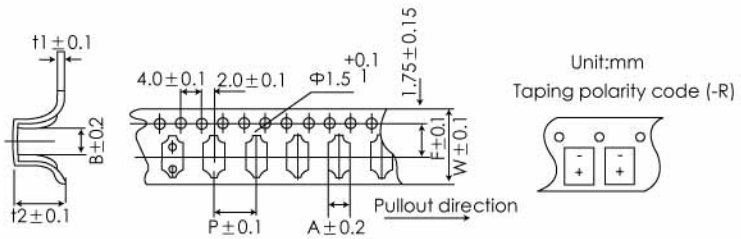
ΦD	f±0.1
Φ10,12.5	1.1
Φ16,18	1.3



FT(Φ3,4,5,6.3,8)

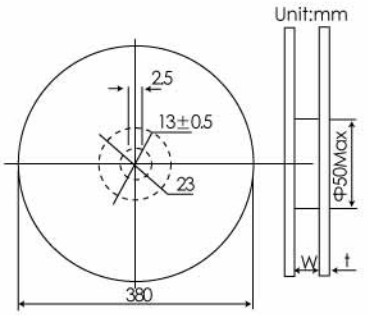


▪ Taping Dimensions



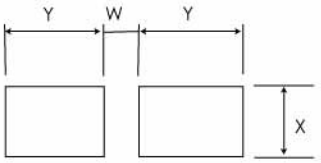
Size (DxL)	Case Code	W	A	B	P	t2	F	t1
3x5.3	B55	12	3.4	3.5	8	5.9	5.5	0.4
4x5.3	D55	12	5.0	5.0	8	5.8	5.5	0.4
5x5.3	E55	12	6.0	6.0	12	5.8	5.5	0.4
6.3x5.3	F55	16	7.0	7.0	12	5.8	7.5	0.4

▪ Reel Dimensions



Size(DxL)	V	Reel size		Quantity in a reel(PCS.)
		W	t	
3x5.3	B55	14	3	2000
4x5.3	D55	14	3	2000
5x5.3	E55	14	3	1000
6.3x5.3	F55	18	3	1000

Recommended Pad Pattern and Size

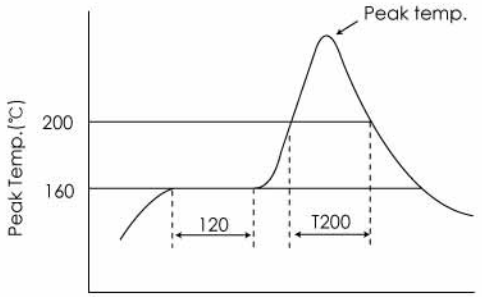


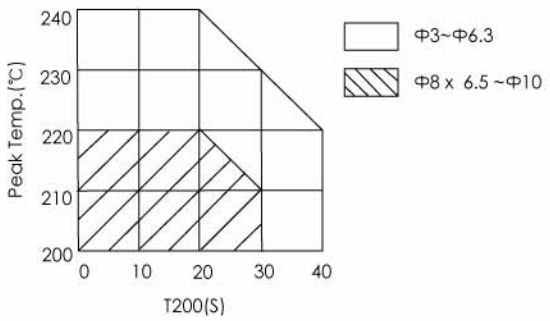
Unit:mm

Size ΦDxL	Case Code	Land Size		
		X	Y	W
3x5.3	B55	1.6	2.2	0.8
4x5.3	D55	1.6	2.6	1.0
5x5.3	E55	1.6	3.0	1.4
6.3x5.3	F55	1.6	3.5	1.9

Recommended Soldering Methods

Method	Reflow Soldering	Soldering Iron	Flow Soldering
Advisability	○ Recommended	○ Recommended	× Not Recommended





(1)Method is as follows.

Reflow soldering condition.

They following temperature profile condition should be observed for soldering. (For higher temperature, please contact us after measuring the capacitor's product temperature profile at your side.)

Product temperature will rise slower as the product size gets bigger.

It is not necessary to adjust the reflow furnace temperature setting according to the product size, for example, Φ4 and Φ10 products can be mixed on one PCB for reflowing.

(2)Soldring precautions

1)Elements related to the reflow soldering temperature

- Product size:The temperature rises slower as the size gets bigger.
- Product location:The center part of the PCB edges.
- PCB size:The PCB temperature rises slower as the area and/or thickness of the PCB gets greater.

2)Repeated reflowing

- Avoid reflowing twice if possible.
- If repeated reflowing is unavoidable, contace us after measuring the first and thd secong reflow profiles and thd reflow interval at your side.
- Do not attempt to reflow three times.

3)Soldering with soldering iron

Observe the following conditions.

- The iron tip temperature:350±5
- Soldering time:3^{+1}_{0} . seconds.